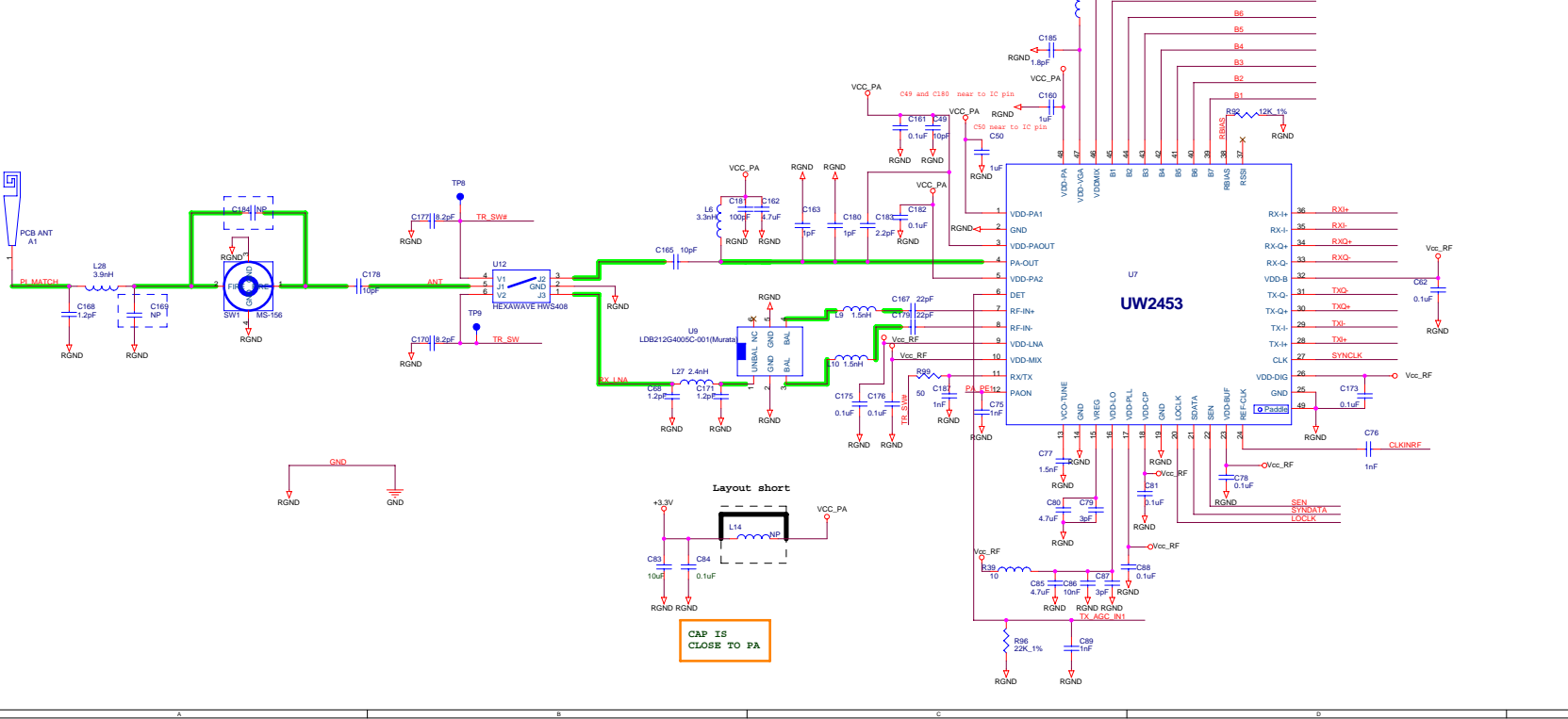


PCB STACK-UP FOR USB DONGLE

LAYER 1	1 OZ Cu
	FR4--7 mil
LAYER 2	1 OZ Cu
	FR4--20 mil
LAYER 3	1 OZ Cu
	FR4--7 mil
LAYER 4	1 OZ Cu

50 Ohm RF thickness line 13 mil width
 Note: the PCB material: FR4 Er= 4.5
 PCB Total thickness=1mm



ZyDAS Technology Corporation		
TITLE:		
DRN:	DWG NO:	
CKD:	REV:	
APPD:	SHEET 1 OF 1	
Amendment History		
Date	Release	Description
2006/05/16	AA00	FIRST DESIGN
2006/06/12	AC01	tune RF performance
2006/07/20	AC02	tune RF performance
Section ALL Circuit		
Size	Document Number	Rev
Custom	45-401-10191AC02	01
Date: Wednesday, October 25, 2006 Sheet 1 of 1		